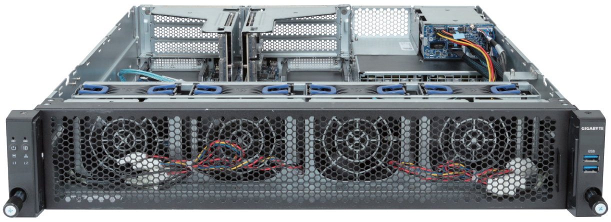
GIGABYTE™

E263-S30-AAV1

Edge Server - 2U UP 2 x PCIe Gen5 GPUs

intel. xeon



Features

- Single 5th/4th Gen Intel® Xeon® Scalable Processors
- Single Intel® Xeon® CPU Max Series
- 8-Channel DDR5 RDIMM, 16 x DIMMs
- Dual ROM Architecture supported
- 1 x 1Gb/s LAN port via Intel® I210-AT
- 2 x 2.5" Gen4 NVMe/SATA/SAS hot-swap bays on the rear side
- 1 x M.2 slot with PCIe Gen3 x4 interface
- 2 x FHFL PCIe Gen5 x16 slots for GPUs
- 2 x OCP 3.0 Gen5 x16 slots
- 1+1 1600W 80 PLUS Titanium redundant power supplies

Application

Edge, AI, Visual Computing, Networking, Hybrid/Private Cloud...

Specification

Dimensions	2U (W438 x H87.5 x D520 mm)
Motherboard	MS33-DC0
CPU	5th/4th Generation Intel® Xeon® Scalable Processors Intel® Xeon® CPU Max Series Single processor, TDP up to 350W
Socket	1 x LGA 4677 (Socket E)
Chipset	Intel® C741 Chipset
Memory	16 x DIMM slots, 8-Channel DDR5 memory RDIMM up to 96GB; 3DS RDIMM up to 256GB Memory speed: Up to 5600 MT/s (1DPC), 4400 MT/s (2DPC)
LAN	1 x 1Gb/s LAN port (1 x Intel® I210-AT) - Supports NCSI function 1 x 10/100/1000 Mbps Management LAN
Video	ASPEED® AST2600 Integrated 2D Graphic Adapter
Storage	Rear: 2 x 2.5" Gen4 NVMe/SATA/SAS hot-swappable bays *SAS card is required for SAS devices support 1 x M.2 slot (M-key, PCIe Gen3 x4, supports 2280/22110 cards)
RAID	Intel® SATA RAID 0/1/10/5
Expansion Slots	2 x FHFL PCIe Gen5 x16 slots for GPUs 2 x OCP 3.0 Gen5 x16 slots - Supporte NCSI function
Backplane Board	Speed and bandwidth: PCIe Gen4 x4 or SATA 6Gb/s or SAS 12Gb/s
TPM	1 x TPM header with SPI interface - Optional TPM2.0 kit: CTM010

I/O Ports	Front: 2 x USB 3.2 Gen1 Rear: 2 x USB 3.2 Gen1, 1 x Mini-DP, 1 x RJ45, 1 x MLAN Internal: 1 x TPM header, 1 x VROC connector
Power Supply	1+1 1600W 80 PLUS Titanium redundant power supplies AC Input: 100-240V
System Management	ASPEED® AST2600 management controller GIGABYTE Management Console (AMI MegaRAC SP-X)
OS Compatibility	Windows Server 2019 / 2022 RHEL 8.6 / 8.7 / 8.8 / 8.9 /8.10 / 9.0 / 9.1 / 9.2 / 9.3 / 9.4 SLES 15 SP4 / SP5 / SP6 Ubuntu 22.04 / 22.04.1 / 22.04.2 / 22.04.3 / 22.04.4 / 24.04 LTS VMware ESXi 7.0 Update 3o / 8.0 Update 1, Update 2, Update 3 Citrix Hypervisor 8.2 LTSR CU1
System Fans	4 x 80x80x38mm (18,300rpm)
Operating Properties	Operating temperature: 10°C to 35°C Operating humidity: 8-80% (non-condensing) Non-operating temperature: -40°C to 60°C Non-operating humidity: 20%-95% (non-condensing)
Packaging Content	1 x E263-S30-AAV1, 1 x CPU heatsink, 3 x Carrier clips, 1 x Mini-DP to D-Sub cable, 2 x GPU power cables (2x PCIe 8pi) Packaging Dimensions: 989 x 594 x 279 mm
Part Numbers	Barebone package (5th/4th Gen): 6NE263S30DR000ABV1* Barebone package (4th Gen): 6NE263S30DR000AAV1* - CPU heatsink: 25ST1-4Z3200-S7R - Mini-DP to D-Sub cable: 25CRN-200801-K1R - Power supply: 25EP0-21600E-L0S - 2-Section Rail kit (385-480mm): 25HB2-3A0204-K0R (Optional) - 2-Section Rail kit (660-840mm): 25HB2-3A0203-K0R (Optional)

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